

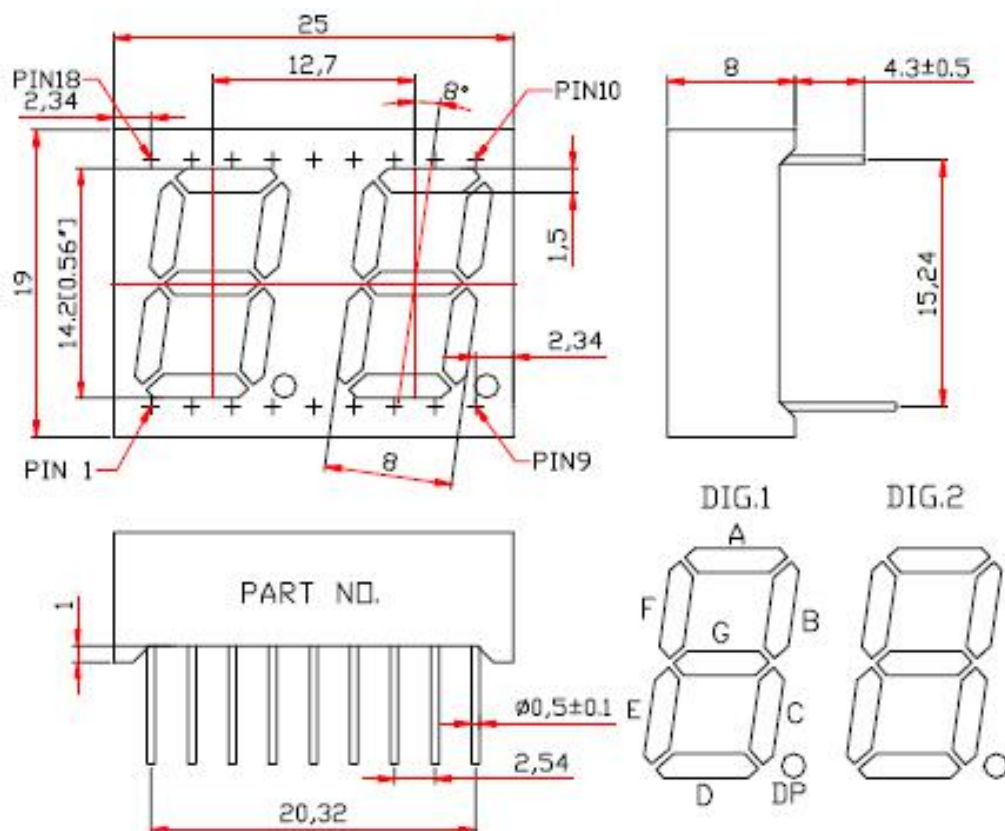
WCN2-0056WW-A11**SPECIFICATION**

WCN			CUSTOMER Confirmed
Prepared by	Checked by	Approved by	
Wei 2021-6-10	Athena	William	
REVISION RECORD			



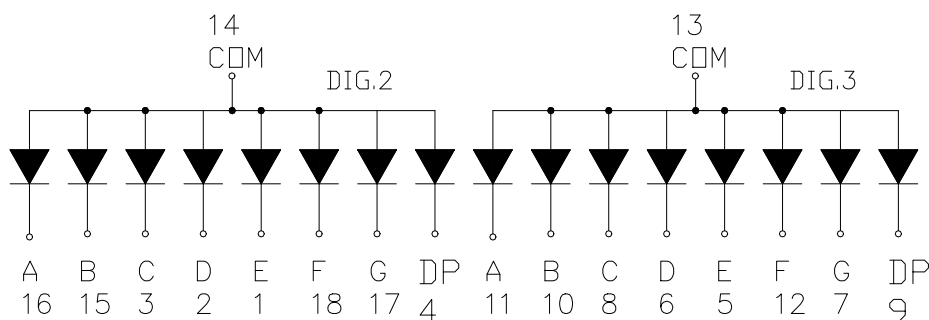
REVISION: A0

Outer Dimension:



Notes: Unless otherwise stated, the tolerance is $\pm 0.25\text{mm}$.

Circuit Diagram



Pin Connection:

PIN NO.	CONNECTION	PIN NO.	CONNECTION	PIN NO.	CONNECTION
1	Cathode 1E	7	Cathode 2G	13	Common Anode Dig2
2	Cathode 1D	8	Cathode 2C	14	Common Anode Dig1
3	Cathode 1C	9	Cathode DP2	15	Cathode 1B
4	Cathode DP1	10	Cathode 2B	16	Cathode 1A
5	Cathode 2E	11	Cathode 2A	17	Cathode 1G
6	Cathode 2D	12	Cathode 2F	18	Cathode 1F

■ Features:

- High Reliability
- Color: White
- Low Power Requirement
- Easy Assembly

■ Description:

- Dual Digit Display
- Digit Height:14.2 mm (0.56")
- Black Face and White Segment

■ Absolute Maximum Rating (Ta=25°C):

Parameter	Symbol	Condition	Color	Rating	Units
Power Dissipation Per Segment	P _d	—	White	85	mW
Forward Current Per Segment	I _F	—	White	25	mA
Peak Forward Current Per Segment	I _{FP}	1/10 Duty 10KHz	White	100	mA
Reverse Voltage Per Segment	V _R	—	White	5	V
Operating Temperature Range	T _{opr}	—	—	-35~+85	°C
Storage Temperature Range	T _{stg}	—	—	-35~+85	°C

■ Electrical/Optical Characteristics Rating(Ta=25°C)

Item	Symbol	Test conditions	Location	Color	Rating			Units
					Min.	Typ.	Max.	
Forward Voltage	V _F	I _F =20mA	Per Dice	White	2.60	3.30	3.40	V
Luminous Intensity	I _v	I _F =20mA	Per Dice	White	400	600	800	mcd
CIE Coordinate	X	I _F =20mA	Per Dice	White	—	0.2710	—	—
	Y				—	0.2804	—	
Spectral Line Half Width	△λ	I _F =20mA	Per Dice	White	—	25	—	nm

■ Soldering Conditions: Soldering Temp. ≤+260°C, Soldering Time. ≤3sec.

(at 2mm Distance from The Case of Reflector Edge)

LED Displays Reliability Test:

CLASSIFICATION	TEST ITEM	DESCRIPTION AND TEST CONDITION
ENDURANCE TEST	OPERATION LIFE	EVALUATES RESISTANCE OF THE DEVICE WHEN OPERATED AT ELECTRICAL STRESS T _a = UNDER ROOM TEMPERATURE I _F = I _F max
	HIGH TEMPERATURE HIGH HUMIDITY STORAGE	EVALUATES MOISTURE RESISTANCE OF THE DEVICE WHEN STORED FOR A LONG TERM AT HIGH TEMPERATURE AND HUMIDITY T _a = 65±5°C RH=90~95%RH TEST TIME=240± 2Hrs
	HIGH TEMPERATURE STORAGE	EVALUATES DEVICE DURABILITY FOR LONG TERM STORAGE IN HIGH TEMPERATURE T _a = 85±5°C(COB: T _a =65±5°C) TEST TIME=1000Hrs(-24Hrs, +72Hrs)
	LOW TEMPERATURE STORAGE	EVALUATES DEVICE DURABILITY FOR LONG TERM STORAGE IN LOW TEMPERATURE T _a = -35±5°C TEST TIME=1000Hrs(-24Hrs, +72Hrs)
ENVIRONMENTAL TEST	TEMPERATURE CYCLING	EVALUATES RESISTANCE OF DEVICE AT THERMAL STRESSES OR EXPANSION AND CONTRACTION 85°C ~ 25°C ~ -35°C ~ 25°C 30min 5min 30min 5min 10 CYCLES(COB: T _{hot} =65°C, T _{cold} =-25°C)
	THERMAL SHOCK	EVALUATES DEVICE STRUCTURE AND STRUCTURE AND MECHANICAL RESISTANCE WHEN SUDDENLY EXPOSED AT SERVE CHANGES 85±5°C ~ -35±5°C 10min 10min 10 CYCLES(COB: T _{hot} =65°C, T _{cold} =-25°C)
	SOLDERABILITY	EVALUATES SOLDERABILITY ON LEADS OF DEVICE T.SOL=230±5°C DWELL TIME=5±1sec.
	SOLDER RESISTANCE	EVALUATES RESISTANCE TO THERMAL STRESS CAUSED BY SOLDERING T.SOL=260±5°C DWELL TIME=10±1sec.

Packing method A:

102 pcs / Red Expandable Polyethylene.

610 pcs / Box(360*175*130mm).

3660 pcs / Carton(550*380*280mm).

Packing method B:

20 pcs / IC Tube.(520*24.3*19.3)

840 pcs / Box(537*175*125mm).

3360 pcs / Carton(550*380*280mm).